



(51) International Patent Classification:

F27B 9/30 (2006.01) *F27D 1/16* (2006.01)
B23K 1/008 (2006.01) *F27D 17/00* (2006.01)
F27B 9/32 (2006.01) *H05K 3/34* (2006.01)
F27B 9/34 (2006.01)

(21) International Application Number:

PCT/US2013/034234

(22) International Filing Date:

28 March 2013 (28.03.2013)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

13/437,530 2 April 2012 (02.04.2012) US

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(81) Designated States (unless otherwise indicated, for every
kind of national protection available): AE, AG, AL, AM,
AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY,
BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM,
DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT,
HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP,
KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD,
ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI,
NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU,
RW, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ,
TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA,
ZM, ZW.

(84) Designated States (unless otherwise indicated, for every
kind of regional protection available): ARIPO (BW, GH,
GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, SZ, TZ,
UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ,
TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK,
EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV,
MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM,
TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW,
ML, MR, NE, SN, TD, TG).

Declarations under Rule 4.17:

— as to applicant's entitlement to apply for and be granted a
patent (Rule 4.17(ii))

Published:

— with international search report (Art. 21(3))

(54) Title: REFLOW OVEN AND METHODS OF TREATING SURFACES OF THE REFLOW OVEN

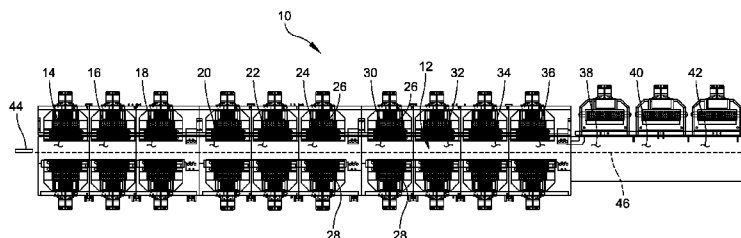


FIG. 1

(57) Abstract: A reflow oven used to join electronic components to a substrate includes a chamber housing having surfaces that are in contact with heated air mixed with contaminants, including flux, and an intermediate layer selectively applied to the surfaces of the chamber housing. The reflow oven may include fabricating the intermediate layer with a foam material, including foaming polymers, e.g., epoxy, polyurethane, polyester, and silicone, or a non-foam material, including non-foaming polymers, e.g., polytetrafluoroethylene and polyimide. A method of treating surfaces of a reflow oven exposed to contaminants, including flux, is further disclosed.